Stress simulation on a round wheel W target

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Outline

- Introduction
- Simulation results of full ring and sliced ring
- Summary

Introduction

• Main structure of the model



- For model 1, there is no slots in tungsten part;
- For model 2, the tungsten is sliced to 10 parts by the slot with a width of 0.2mm;
- An intermetallic contact between the W and the Cu, like brazing, is assumed, with a thermal conductance of 2 W/(cm^2 •K)
- The average power is deposited uniformly in time and space over the top part of the W. In total about 35 Kw
- The water temperature is 50K.

Model-1

Model-1



• Boundaries:

- Water Temperature: 50C
- Thermal Conductance for both of water-Cu and W –Cu surface: 0.02W/mm^2
- Power is only deposited in the top part of the W with 0.0795W/mm^3
- There is a Cu bar with diameter of 30mm in the center. We fixed it.



Results: Temperature distribution





Temperature

There will be a temperature jump at the interface.



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Temperature



The temperature is obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Results: v. M. Stresses



v. M. stresses





The v. M. stresses



The v. M. stresses are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.



The stresses at radial direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma phi



The stresses at phi direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma z



The stresses at axial direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.



Model-2: Sliced W-target with 10 gaps of 0.2mm

Model-2: sliced W-target with 10 gaps of 0.2mm



Results: Temperature distribution



They are essentially the same as in the full ring, as expected.

Results: Stresses



v. M. Stresses distribution at interface



v. M. stress in-plane of contact surface at W wheel

v. M. stress in-plane of contact surface at Cu wheel

Stresses at center of the sector





The v. M. stresses

- The v. M. stresses are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.
- There a binning problem. It should not be a real data.

Sigma r



The stresses at radial direction (sigma x) are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma phi



The stresses at phi direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma z



The stresses at axial direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Stresses at end of the sector



Path for W is on the surface of W due to gaps

The v. M. stresses



- The v. M. stresses are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.
- Path for W is on the surface of W due to the gaps.
- Discussion: the max. stress in this picture appearing at the point shown in the picture is about 164Mpa. However, the max. stress for whole model is about 208MPa. It appears at the similar point in one of connection positions between gaps and Cu cooler.

Sigma r



The stresses at radial direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma phi



The stresses at phi direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Sigma z



The stresses at axial direction are obtained at the surfaces which are both 0.1mm off the interface for Cu and W.

Stresses check near the interface at end of the sector

- Model: it is the same as model-2
- The v. M. stresses at end-surface are calculation near the interface at end of sector



So, we check the paths as following:





Path at interface :

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v. M. stress for W



W:

(-0.2, 220, -20.1) to (-0.2, 240, -20.1) (-0.4, 220, -20.1) to (-0.4, 240, -20.1) (-0.6, 220, -20.1) to (-0.6, 240, -20.1) (-0.8, 220, -20.1) to (-0.8, 240, -20.1) (-1.0, 220, -20.1) to (-01.0, 240, -20.1)

Along the interface at tungsten



v. M. stress for Cu



v. M. stress for W



(-1.0, 220, -20.2) to (-1.0, 240, -20.2) (-1.0, 220, -20.4) to (-1.0, 240, -20.4) (-1.0, 220, -20.6) to (-1.0, 240, -20.6) (-1.0, 220, -20.8) to (-1.0, 240, -20.8) (-1.0, 220, -21) to (-1.0, 240, -21)

The path at interface is 1mm far from end section.

▲ Path at interface:



v. M. stress for Cu



Comparison and Conclusion

			Peak v.M stress (MPa)	Stresses at interface (Mpa)			
		tempature(°C)		v.M.stress	sigma r	sigma phi	sigma z
	interface for W	- 377 at W	251 at W	40 to 130	20 to 120	-50 to 150	-15 to 10
Full ring	interface for Cu			65 to 125	-30 to 10	-140 to -50	-12 to 0
Sliced ring	interface near center of section for W	380 at W	208 at interface	40 to 100	20 to 80	40 to 100	-3 to 7
	interface near center of section for Cu			80 to 135	-10 to 25	-130 to -50	-2 to 13
	interface near end surface of section for W			20 to 150	-90 to 10	-30 to 15	-45 to -4
	interface near end surface of section for Cu			90 to 130	-90 to -30	-140 to -100	-5 to 1





- Sliced ring suffer much less stress.
- However, we need to pay attention to the interface. This can lead to fatigue and thus to loss of thermal contact.

Thanks !